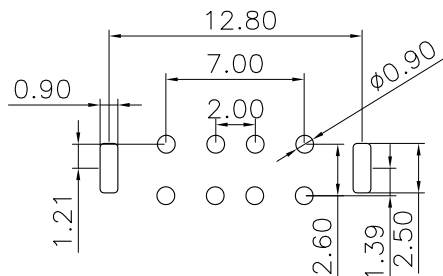
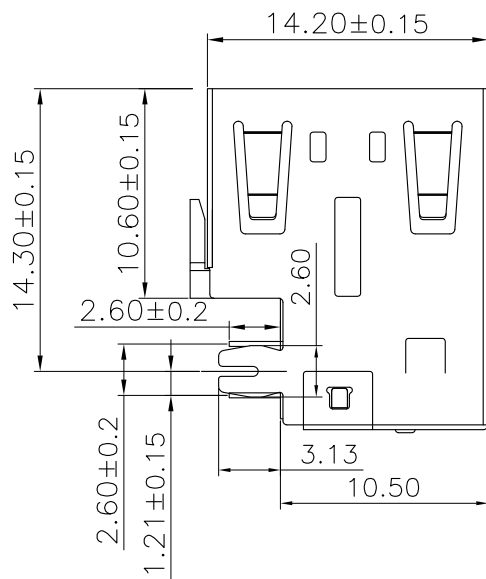
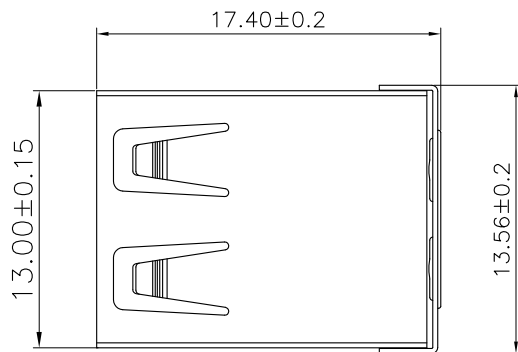
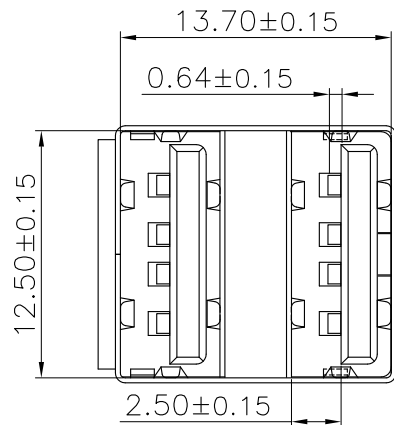


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS



RECOMMENDED P.C.B LAYOUT P.C.B THICKNESS=1.2mm(TOLERANCE=±0.05)

NOTE:

1.MATERIAL SPECIFICATION:

- 1-1.HOUSING:PBT/LCP
- 1-2.CONTACTS:C2680H.
- 1-3.SHELL: SPCC

2.PLATING SPECIFICATION:

- 2-1.CONTACTS:
Ni UNDER PLATED OVER ALL.
Sn MIN ON SOLDER AREA
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

- 2-2. SHELL:
Cu UNDER PLATED OVER ALL.
Ni MIN ON SOLDER AREA

3.MECHANICAL PERFORMANCE:

- 3-1.INSERTION FORCE: 3.57kgf MAX
- 3-2.REMOVAL FORCE: 1.02kgf MIN
- 3-3.DURABILITY: 1500 CYCLES.

4.ELECTRICAL PERFORMANCE:

- 4-1.CURRENT RATING:1.5A
- 4-2.VOLTAGE RATING:30V MAX
- 4-3.CONTACT RESISTANCE: 30m Ohm MAX.
- 4-4.INSULATION RESISTANCE: 1000MΩ MIN
- 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 500V AC MIN.

5.ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -20°C~+85°C.

6.P/N:

WLU2F9-08 1 X X X 158

PLATED: 1-G/F
2-Au 3u"
5-Au 15u"
6-Au 30u"
HOUSING: 1-PBT
2-LCP
COLOUR: A-BLACK
K-WHITE
D-ORANGE

REV.	REVISION RECORD	DATE	UNIT:mm	GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	 WanLian Teconology Co., Ltd
A0	NEW RELEASE	21.01.13		SIZE: A4	LINEAR	ANGLES	APPROVED	Wang_jr	21.08.01	WLU2F9-081XXX158	
			0.00±0.25		X°±3°	DESIGNER	Han_Gao	21.08.01	TITLE: USB2.0 A/F DOUBLE DIP L=17.4mm		
			0.000±0.10	X°X' ±2°	DRAWN	Zijun_Huang	21.08.01				REV: A0 SHEET: 1/1